P	CN N	lumb	per:	2016041	00	0	ı	PCN Date:		4/25/2016			
Ti	tle:		Datasheet for	ADS1246, ADS1247, ADS1248							•		
Cı	ısto	mer	Contact:	PCN Manage			e	ept: Quality Service					
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T			embly Site		Ιſ		Design	Γ	1	Wafer	Bumi	n Site	
F		Assembly Process				X	Data Sheet	Ė	Ť	Wafer Bump Material			
	Assembly Materials			Ì		Part number change	Ī	٦	Wafer Bump Process				
	Mechanical Specification			Ì		Test Site	Ī	Ī	Wafer Fab Site				
		Packing/Shipping/Labeling					Test Process	Ī		Wafer Fab Materials			
									Ī	Wafer Fab Process			
Notification Details													
Description of Change:													
Texas Instruments Incorporated is announcing an information only notification etc.													
- 2.122 2.123. 2.1.24. por acoustic announcing an information only hourisation occi													
The product datasheet(s) is being updated as summarized below.													
The following change history provides further details.													
• • •				ory provide	.5 1	uı	ther details.						
TEXAS ADS1246, ADS1247, ADS1248													
		INST	RUMENTS							ST 2008-RE\			
Changes from Revision G (October 2011) to Revision H Page													
	Add	ed <i>ESI</i>	D Ratings table, Fea	ture Description	sec	ctio	n, Device Functional Modes, Application	on	an	d Impleme	ntation		
	section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section												
	Updated Features and Description sections to include use in applications other than temperature measurement												
	-		•				5, ADS1147, and ADS1148; changed t						
	Merged all <i>Pin Functions</i> into one table, changed IOUT1 and IOUT2 to IEXC1 and IEXC2 to match figures												
Changed compliance voltage for excitation current sources in <i>Electrical Characteristics</i> , now refers to Figure 41 and Figure 42; changed initial error and initial mismatch to absolute error and absolute mismatch													
	_		•				changed timing references to t _{CLK}						
			_										
	Changed order of <i>Typical Characteristics</i> curves to match order in <i>Electrical Characteristics</i> table												
	Added cross-reference for Equation 1 in <i>Noise Performance</i> section												
							added <i>Table 7</i> ; added <i>PGA Common-</i> .						
							culation Example sections					26	
•	Added f _{CLK} /f _{MOD} column to Table 9								30				
•	Added cross-reference for Equation 15 to Power-Supply Monitor section								35				
•	Added cross-reference for Equation 16 to External Voltage Reference Monitor section									35			
•	Added Device Functional Modes section									36			
•	Corrected values in Table 15 to remove extra 0 in 800000h												
•	Add	ed text	to Chip Select secti	on to say that S	CL	< w	ill force \overline{DRDY} high, even with \overline{CS} high	١				41	
•	Added text to Data Output and Data Ready section to say that stop read data continuous mode is not compatible with DRDY MODE set to 1								42				

show full command and DRDY/DOUT falling with NOP									
Added more infomation to Data Format section; added Figure 77	44								
Added cross-reference for Figure 78 to Commands section	45								
Modified Figure 78 to include CS status through SLEEP and WAKEUP command	46								
Updated Figure 79 and Figure 80 to show start of command execution	46								
Added cross-reference for Figure 83 to Commands section	47								
Removed figure for SDATAC (Stop Read Data Continuous) command	47								
Updated Figure 85 to show MUX1 as the start of the data byte for the given command and register local	ation 48								
Updated Figure 86 to show start of calibration timing									
Updated Register Maps section to new format									
Updated Application Information section. Included new typical applications for Ratiometric 3-Wire RTD Measurement System and K-Type Thermocouple Measurement (-200°C to +1250°C) with Cold-Junction Compensation									
Updated Figure 112 and Figure 113 to better show timing information									
Removed Hardware-Compensated 3-Wire RTD Measurement application section									
The datasheet number will be changing.									
Device Family Change From:	Change To:								
ADS1246, ADS1247, ADS1248 SBAS426G	SBAS426H								
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/ADS1248									
Reason for Change:									
To more accurately reflect device characteristics.									
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):									
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.									
Changes to product identification resulting from this PCN:									
None.									
Product Affected:									

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

ADS1247IPW

ADS1246IPWR

ADS1248IPWR

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